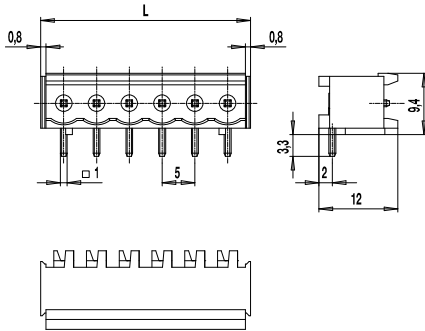


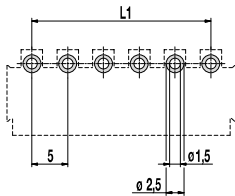
Pin strip for THR

120-M-211-THR

Plug-in direction parallel to PCB, with side walls



PCB Layout



L1 = (No. of poles - 1) x pitch
 Solder paste thickness: 0,15 - 0,2 mm
 Solder pad diameter: ø 2,5 mm

The products based on our established 120 series (Conecta) have been designed for the soldering process in Through-Hole-Reflow technology. The soldering paste is applied to the plated through holes and the pins are placed in the circuit board and soldered by a reflow oven. The terminal mouldings are made of heat-resistant material. The stand-offs on the base ensures there is enough room for the soldering paste and facilitates good heat circulation for optimum soldering and enables the soldering joint to be visually inspected. The solder pin projects very slightly with a circuit board thickness of 1,6 mm, creates a solder point on both sides, and thus guarantees a secure mounting. The position of the solder pins enables an equally minimal allocation area on the circuit board as with wave soldering.

Part Numbers

No. of poles	120-M-211-THR	Length	Pcs
2	10.806.352	12,00	200
3	10.806.353	17,00	200
4	10.806.354	22,00	100
5	10.806.355	27,00	100
6	10.806.356	32,00	100
8	10.806.358	42,00	50
10	10.806.360	52,00	50
12	10.806.362	62,00	50

further number of poles on request

General Information

Pitch	5 mm
No. of poles	2 - 12
Usable with	all plug connectors of series 120
Additional Information	The 120-M-THR headers are, like the conventional products, available with straight or angled soldering pins for vertical or parallel plugging of the mating parts, whereby all plugs of the Conecta series 120-A, -D, and -F can be used.

Technical Data

Overvoltage Category	III	III	II
Pollution Severity Level	3	2	2
Rated Voltage	250 V	320 V	630 V
Rated Impulse Voltage	4 kV	4 kV	4 kV
Rated Insulation Voltage	250 V acc. to EN 60998-1		
Rated Current	12 A		
Soldering process	Wave solder & reflow solder		
Hole in PCB	ø 1,5 mm		
PCB thickness	Wave solder max. 1,6 mm; reflow solder 1,6 - 3,2 mm		

Material

Moulding	PA HT, black, V-0
Comparative Tracking Index	CTI ≥ 600
Insulating Group	I
Temperature Range	-40°C up to 150°C; reflow solder temperature (Peak) max. 260°C (15-30 s)
Solder pin	1,0 x 1,0 mm; tin plated brass

Approvals

	Current	Voltage	Group	AWG	Nm
	15	300	B		
	10	300	D		
	15	300	B		
	10	300	D, E		

Options / Accessories

- Consecutive numbering
- Special marking according to drawing
- Self-adhesive marking strip BST-5,00 [1]
- Special packaging on request: Tape-on-Reel - Tray - Tube magazine

[1] To be fitted after reflow soldering process